

Description

The AP4A025M uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

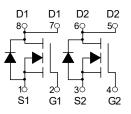
 $V_{DS} = 40V I_D = 12A$ $R_{DS(ON)} < 20m\Omega @ V_{GS} = 10 V$ $R_{DS(ON)} < 16m\Omega @ V_{GS} = 4.5V$

Application

Battery protection Load switch Uninterruptible power supply



SOP-8



Dual N-Channel MOSFET

Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) |
|------------|-------|------------|----------|
| AP4A025M | SOP-8 | HXY MOSFET | 3000 |

Absolute Maximum Ratings@Tj=25°C(unless otherwise specified)

| Symbol | Parameter | Rating | Units |
|--------------------------------------|---|-------------|-------|
| V _{DS} | Drain-Source Voltage | 40 | V |
| V _{GS} | Gate-Source Voltage | <u>+</u> 20 | V |
| I₀@T₄=25℃ | Drain Current, V _{GS} @ 4.5V ³ | 12 | A |
| I₀@T₄=70°C | Drain Current, V _{GS} @ 4.5V ³ | 7 | A |
| Ідм | Pulsed Drain Current ¹ | 40 | А |
| P _D @T _A =25°C | Total Power Dissipation | 2.9 | W |
| Тѕтс | Storage Temperature Range | -55 to 150 | °C |
| TJ | Operating Junction Temperature Range | -55 to 150 | °C |
| Rthj-a | Maximum Thermal Resistance, Junction- ambient ³ | 65 | °C/W |



| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|------------------------------------|---------------------|---|-----|------|------|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250µA | 40 | - | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =40V,V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V_{GS} =±20V, V_{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250µA | 1 | 1.5 | 2.0 | V |
| Drain-Source On-State Resistance | Р | V _{GS} =10V, I _D =8A | - | 16 | 20 | mΩ |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =4.5V, I _D =4A | - | 18.9 | 24 | mΩ |
| Forward Transconductance | g fs | V _{DS} =5V,I _D =8A | 33 | - | - | S |
| Dynamic Characteristics (Note4) | | | • | | | |
| Input Capacitance | C _{lss} | | - | 964 | - | PF |
| Output Capacitance | C _{oss} | V _{DS} =20V,V _{GS} =0V, F=1.0MHz | - | 109 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | | - | 96 | - | PF |
| Switching Characteristics (Note 4) | | | • | | | |
| Turn-on Delay Time | t _{d(on)} | | - | 5.5 | - | nS |
| Turn-on Rise Time | tr | V_{DD} =20V, R _L =2.5 Ω | - | 14 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | V_{GS} =10V, R_{GEN} =3 Ω | - | 24 | - | nS |
| Turn-Off Fall Time | t _f | | - | 12 | - | nS |
| Total Gate Charge | Qg | N/ 00\/L 0A | - | 22.9 | - | nC |
| Gate-Source Charge | Q _{gs} | $V_{DS}=20V, I_{D}=8A,$ | - | 3.5 | - | nC |
| Gate-Drain Charge | Q _{gd} | V _{GS} =10V | - | 5.3 | - | nC |
| Drain-Source Diode Characteristics | I | | · | | | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V,I _S =9A | - | 0.8 | 1.2 | V |

Electrical Characteristics (T_A=25[°]C unless otherwise noted)



Typical Electrical and Thermal Characteristics (Curves)

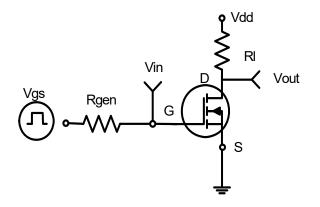
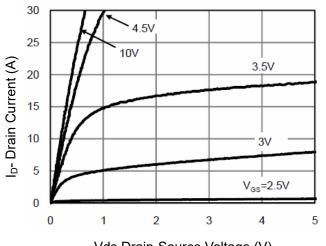
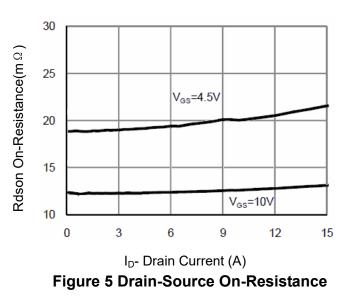


Figure 1:Switching Test Circuit



Vds Drain-Source Voltage (V) Figure 3 Output Characteristics



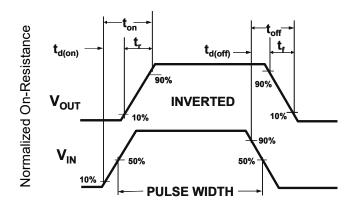


Figure 2:Switching Waveforms

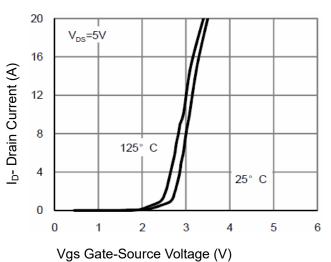


Figure 4 Transfer Characteristics

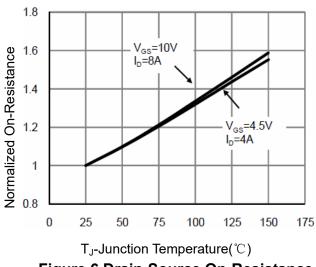
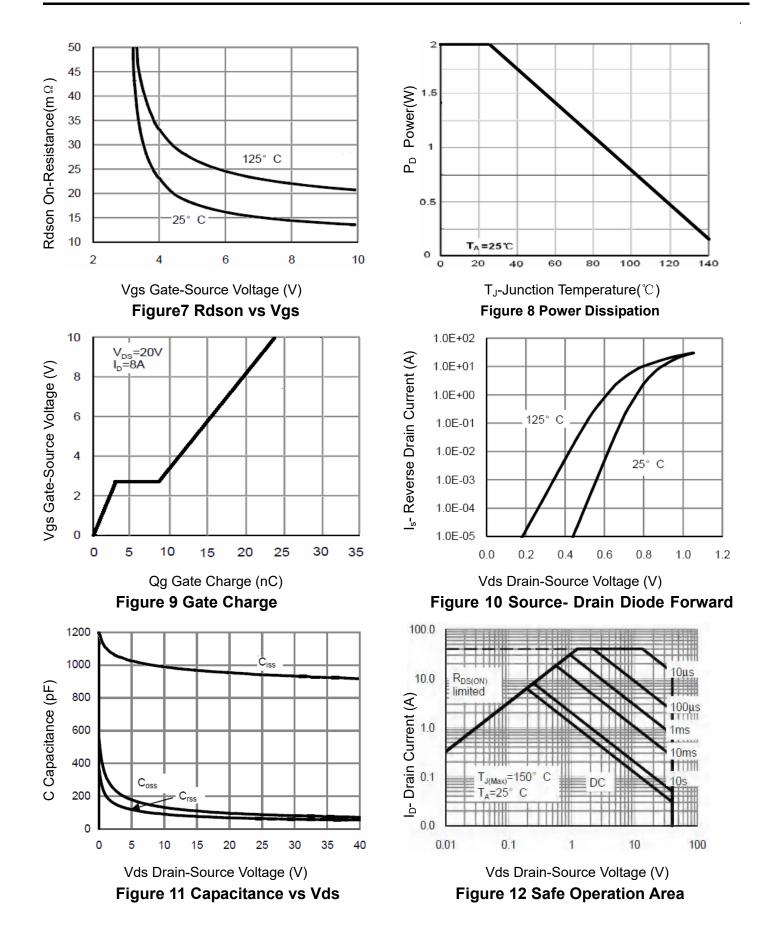
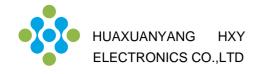


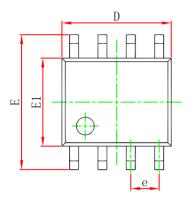
Figure 6 Drain-Source On-Resistance

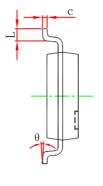


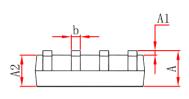




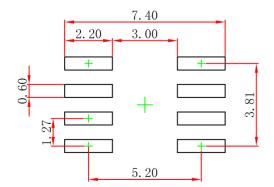
SOP-8 Package Outline Dimensions







| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|-------|----------------------|-------|--|
| | Min | Max | Min | Max | |
| А | 1.350 | 1.750 | 0.053 | 0.069 | |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 | |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 | |
| b | 0.330 | 0.510 | 0.013 | 0.020 | |
| с | 0.170 | 0.250 | 0.007 | 0.010 | |
| D | 4.800 | 5.000 | 0.189 | 0.197 | |
| e | 1.270 (BSC) | | 0.050 (BSC) | | |
| E | 5.800 | 6.200 | 0.228 | 0.244 | |
| E1 | 3.800 | 4.000 | 0.150 | 0.157 | |
| L | 0.400 | 1.270 | 0.016 | 0.050 | |
| θ | 0 ° | 8° | 0 ° | 8° | |



Note: 1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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